

intel® Technical Advisory

TA-0289-1

5200 NE Elam Young Parkway
Hillsboro, OR 97124

July 12, 2000

C440GX+ High Thermal Readings With Processors

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Products Affected

Product Type	MM ##	Product Code
C440GX+ Boxed Board	821095	BOXC440GX
Spares and Accessories (Dual Retention Module)	821617	AKORETENTION

Description

High processor temperature readings have been reported with some 550mhz Pentium® III Xeon™ processors if they are installed on the C440GX+ baseboard. These readings have only been reported on a few systems utilizing the Pentium III Xeon 550 MHz processors. The high temperature readings can vary between processors and are typically in the range of 50 to 90 degrees centigrade.

The high processor temperatures will be visible through the System Event Log (SEL) entries or through server management software such as Intel Server Control.

Root Cause Investigation

Intel is continuing to investigate root causes for the high temperature readings and believes one of the primary reasons is improper clearance between the retention module base and the processor.

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Corrective Action

Intel is modifying the processor retention module to prevent the high temperature readings. The modification consists of widening the base module slot to allow more room for the processor cartridge. An additional .030" of clearance is being added. The revised processor retention module will be implemented via the standard Product Change Notice procedure.

Unless a system is exhibiting the high temperatures described in this Technical Advisory, there is no need to take any action. The majority of existing system configurations will not experience this problem.

If it has been determined that the anomaly described in this Technical Advisory does exist on a particular system, replacements of Intel processor retention modules will be provided at no charge through the standard warranty replacement procedures.

Please contact your Intel Sales Representative if you require more specific information about this issue.

Server Products Division
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